

LTM2892-BGA, 24LD 9mm X 6.25mm X 2.91mm (TABLE OF MATERIAL DECLARATION)

The LTM2892 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.0567	Barium Compounds	7727-43-7	0.00150	2.64
				Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1 1156-51-0/9003-36-5/21645-51-2 non-disclosure	0.01598	28.18
				Copper Metal	7440-50-8	0.02251	39.70
				Copper Compounds	147-14-8	0.00001	0.02
				Ecotoxic substances	7440-38-2 7440-28-0	0.00000	0.00
				Gold metal or alloy	7440-57-5	0.00009	0.15
				Nickel	7440-02-0	0.00067	1.18
				Zinc	7440-66-6	0.00002	0.03
				Continuous Filament Fiber Glass	65997-17-3	0.01255	22.14
				Acrylic Resin	non-disclosure	0.00285	5.03
				Epoxy Resin	non-disclosure	0.00006	0.11
				Chromium(III) oxide	1308-38-9	0.00000	0.00
				Silica amorphous	7631-86-9	0.00002	0.03
				Talc;not containing fibers like asbestos	14807-96-6	0.00017	0.30
				Aromatic carbonyl compounds	non-disclosure	0.00016	0.29
				Cyanoguanidine	461-58-5	0.00000	0.01
				Amine compounds	non-disclosure	0.00002	0.04
				Leveling agent and others	non-disclosure	0.00007	0.12
				Imidazole system curing reagent	*non-disclosure	0.00001	0.01
				2	Solder Paste	Alloy	0.0032
				Sb	7440-36-0	0.00016	5.00
3	Epoxy		0.0002	Di-ester resin	non-disclosure	0.00002	10.00
				Functionalized ester	non-disclosure	0.00002	10.00
				Silver	7440-22-4	0.00019	80.00
4	Passive/Active Components		0.0270	Copper (Cu)	7440-50-8	0.00864	32.00
				Nickel (Ni)	7440-02-0	0.00216	8.00
				Tin (Sn)	7440-31-5	0.00065	2.40
				Ceramic (Ba) Compounds	12047-27-7	0.01555	57.60
5	Active Ics	Silicon	0.0019	Silicon	7440-21-3	0.00193	100.00
6	Wire	Gold	0.0005	Au	7440-57-5	0.00051	99.99
7	Solder Ball	SAC305	0.0198	Sn	7440-31-5	0.01910	96.50
				Ag	7440-22-4	0.00059	3.00
				Cu	7440-50-8	0.00010	0.50
8	Encapsulation	Epoxy Resin	0.1906	Fused Silica	60676-86-0	0.14714	77.20
				Epoxy Resin	non-disclosure	0.01696	8.90
				Phenol Resin	non-disclosure	0.01696	8.90
				Crytalline Silica	14808-60-7	0.00572	3.00
				Carbon Black	1333-86-4	0.00095	0.50
				Metal Hydroxide	non-disclosure	0.00286	1.50
Total Package Weight			0.3000				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts